

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4670069

| | |
|----------------------------------|--|
| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| | |
| Name | Execution Date |
| YINGCONG DENG | 10/13/2017 |
| LAN GONG | 08/15/2017 |
| QIAN YING | 08/15/2017 |
| DANDAN ZHANG | 08/21/2017 |
| LVHAI HU | 08/21/2017 |
| YUN LIU | 08/21/2017 |
| QINGLONG ZENG | 08/22/2017 |
| YONG YAN | 08/15/2017 |
| RECEIVING PARTY DATA | |
| Name: | TYCO ELECTRONICS (SHANGHAI) CO. LTD. |
| Street Address: | SECTIONS F AND G, LEVEL 1, BLDG 15, NO. 999 YINGLUN ROAD |
| Internal Address: | CHINA (SHANGHAI) PILOT FREE TRADE ZONE |
| City: | SHANGHAI |
| State/Country: | CHINA |
| Name: | MEASUREMENT SPECIALTIES (CHENGDU) LTD |
| Street Address: | NO. 368 WULIANYI ROAD |
| City: | SHENZHEN |
| State/Country: | CHINA |
| Name: | TE CONNECTIVITY CORPORATION |
| Street Address: | 1050 WESTLAKES DRIVE |
| City: | BERWYN |
| State/Country: | PENNSYLVANIA |
| Postal Code: | 19312 |
| Name: | SHENZHEN AMI TECHNOLOGY CO., LTD. |
| Street Address: | 1/F H2 BLDG, HONGFA HI-TECH INDUSTRIAL PARK |
| Internal Address: | TANGTOU BLVD, SHIYAN, BAOAN DISRICT, SHENZHEN |
| City: | GUANGDONG |
| State/Country: | CHINA |
| PROPERTY NUMBERS Total: 1 | |

PATENT

| Property Type | Number |
|---|-----------------------------|
| Application Number: | 15611020 |
| CORRESPONDENCE DATA | |
| Fax Number: | (610)889-3696 |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | |
| Phone: | 610-889-3699 |
| Email: | berwynipdocket@barley.com |
| Correspondent Name: | BARLEY SNYDER |
| Address Line 1: | 2 GREAT VALLEY PARKWAY |
| Address Line 2: | SUITE 110 |
| Address Line 4: | MALVERN, PENNSYLVANIA 19355 |
| ATTORNEY DOCKET NUMBER: | 21334-2502 |
| NAME OF SUBMITTER: | SALVATORE ANASTASI |
| SIGNATURE: | /Salvatore Anastasi/ |
| DATE SIGNED: | 11/02/2017 |
| Total Attachments: 2 source=DengAssnDec#page1.tif source=DengAssnDec#page2.tif | |

US -- United States

IP Portal
30-May-2017
Your Ref: TY-00584 US
Our Ref: P187060.US.01

COMBINED DECLARATION AND ASSIGNMENT

As a below-named inventor, I hereby declare that:

This declaration is directed to inventions and improvements disclosed in:

the attached application, or

United States application or PCT International application number
15/611,020 filed on 01 June 2017
entitled Welding System and Method ("the APPLICATION")

The APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

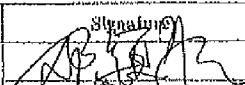

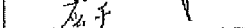
I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56; AND

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

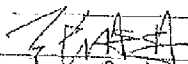
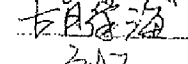
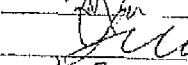
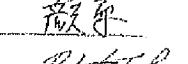
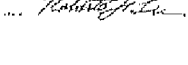

TYCO ELECTRONICS (SHANGHAI) CO. LTD., MEASUREMENT SPECIALTIES (CHENMODU) LTD., TB CONNECTIVITY CORPORATION, SHENZHEN AMI TECHNOLOGY CO., LTD, ("ASSIGNEES"), corporations organized and existing under and by virtue of the laws of China and the United States having their principal place of business at Section 1' and G Level 1 Building 15 No. 999 Yingtun Road, China (Shanghai) Pilot Free Trade Zone, Shanghai, China, and No. 368 Wutianyi Road, Shenzhen, China, and 1050 Westlakea Drive, Berwyn, Pennsylvania, 19312 United States, and I/F, H2 Bldg, Hongfu Hi-tech Industrial Park, Tangliu Blvd, Shiyun, Baoan District, Shenzhen, Guangdong, China 518108,

for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the rights under the International Convention, and all renewals, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment

| Legal Name | Signature | Date |
|---------------|---|------------|
| DIANG, Yihong |  | 2017.10.13 |
| QIONG, Lan |  | 2017.8.15 |
| YANG, Qian |  | 2017-8-15 |

US - United States

IP Portal
30-May-2017
Your Ref: TY-00584 US
Our Ref: P187360,US.01

| | | |
|--------------------------|---|-------------|
| ZHANG, Dandan |  | 2017.8.21 |
| HU, Lvhai |  | 2017.8.21 |
| LIU, Yun |  | 2017.8.21 |
| ZENG, Qinglong |  | 2017.8.22 |
| YAN, Yong |  | 2017.8.15 |
| LU, Roberto Francisco-Yi |  | 20 Aug 2017 |